

## **Quarterly Reliability Monitoring Results**

Quarters: Q1/2022 to Q4/2023

Based on structural similarity

Supplier		User Part Number						
Nexperia B.V. Name of Laboratory Assembly reliability labs Based on AEC-Q101 Test		PBSS4350D-Q Part Description						
		SMD package						
		Test Conditions	Duration	# Lots	# Quantity	# Rejects		
			TEST					
	Pre- and Post-Stress							
# E1	Electrical Test	Tamb = 25 °C	N/A	see below	all parts	see below		
		JESD22-A113						
		Bake Tamb = 125 °C	24 hours					
# A1	PC Preconditioning	Soak Tamb = 85 °C, RH = 85% Reflow soldering	168 hours 3 cycles	1674	70490	0		
# A1	reconditioning	-	5 cycles	10/4	70490	0		
	HTRB	MIL-STD-750-1 M1039 Method A						
		$T_j = T_j max$ , $Vr = 100\%$ of max. datasheet						
# B1	Bias	reverse voltage	1000 hours	415	18680	0		
	тс	JESD22-A104						
# A4	Temperature Cycling	-65 °C to Tjmax, not to exceed 150°C	1000 cycles	343	15360	0		
# A3 <b>or</b> # A3 alt	UHAST Unbiased HAST	JESD22-A118 Tamb = 130 °C, RH = 85 %	— 96 hours	362	15920	0		
	UIDIased HAST							
	AC	JESD22-A102 Tamb = 121 °C, RH = 100 %						
	Autoclave	Pressure = $205 \text{ kPa} (29.7 \text{ psia})$						
# A5 ait								
	H3TRB	JESD22-A101						
	High Humidity High	Tamb = 85 °C, RH = 85%, VR = 80 % of						
# A2 alt	Temperature Reverse Bias	rated reverse voltage <sup>[1]</sup>	1000 hours	343	15360	0		
		MIL-STD-750 Method 1037						
	IOL	ton = toff, devices powered to insure $\Delta Tj$ =						
# A5	Intermittent Operating Life	100 °C for 15000 cycles	1000 hours	343	15360	0		
	BCU							
# 60	<b>RSH</b> Resistance to Solder Heat	JESD22-A111 260 °C ± 5 °C	10 -	202	0.400	0		
# C8	SD		10 s	283	8490	0		
# C10	SD Solderability	J-STD-002		214	6420	0		
# CIU	Solderability	5 515 002		214	0420	U		

[1] The maximum applied voltage is limited by test chamber set up and does not exceed 115V.

## **Calculation of FIT and MTTF**

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test #B1) Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

Wafer Fab	Technology	Quantity	Rejects	Failure Rate (FIT)	MTTF (hrs)
Nexperia DHAM	Small Signal Bipolar Transistor	18680	0	0,23	4,40E+09

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